



Material Content Data Sheet



Sales Product Name		TLE8110EE		Issued		14. September 2018		
MA#		MA003321418						
Package		PG-DSO-36-51		Weight*		610.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.562	2.55	2.55	25483	25483
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		372	
	non noble metal	iron	7439-89-6	4.546	0.74		7443	
wire	non noble metal	copper	7440-50-8	184.568	30.22	31.01	302235	310143
	non noble metal	copper	7440-50-8	2.359	0.39	0.39	3862	3862
	encapsulation	organic material	carbon black	1333-86-4	0.786	0.13		1287
encapsulation	plastics	epoxy resin	-	36.160	5.92		59213	
	inorganic material	silicondioxide	60676-86-0	356.099	58.31	64.36	583121	643621
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8909	8909
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1295	1295
glue	plastics	epoxy resin	-	1.021	0.17		1672	
	noble metal	silver	7440-22-4	3.062	0.50	0.67	5015	6687
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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